

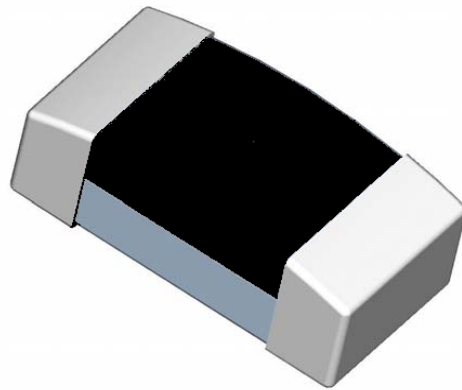
Specification Status: Released

BENEFITS

- ESD protection for high frequency applications (HDMI 1.4)
- Smaller form factor for board space savings
- Helps protect electronic circuits against damage from electrostatic discharge (ESD) events
- Assists equipment to pass IEC 61000-4-2, level 4 testing

FEATURES

- 0.15 pF (typ) Capacitance
- Low leakage current
- Low clamping voltage
- Fast response time (<1ns)
- Capable of withstanding numerous ESD strikes
- Compatible with standard reflow installation procedures
- Thick film technology
- Bi-directional protection



APPLICATIONS

- HDMI 1.4 interface
- LCD, HDTV
- Cellular phones
- Antennas (cell phones, GPS...)
- Portable video devices (PDA, DSC, Bluetooth...)
- Printer ports
- High speed Ethernet
- USB 3.0 and IEEE 1394 interfaces
- DVI interface

CAUTION: This device should not be used in Power Bus applications

MATERIALS INFORMATION

RoHS Compliant

Directive 2002/95/EC
Compliant

ELV Compliant

Directive 2000/53/EC
Compliant

Halogen Free*



Lead Free



* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm

TYPICAL DEVICE RATINGS AND CHARACTERISTICS

Symbol	Continuous Max Operating Voltage	Typical TLP Trigger Voltage ¹	Typical TLP Clamping Voltage ¹ after 30ns	Typical Capacitance ² @ 1 MHz, 1V _{rms}	Typical Leakage Current @14V _{DC}	Max Leakage Current @14V _{DC}
	V _{DC}	V _{T(TLP)}	V _{C(TLP 30)}	C _p	I _{L(Typ)}	I _{L(MAX)}
Unit	V	V	V	pF	μA	μA
Value	05	250	40	0.15	<0.01	10.0

Note 1: TLP test method at 1000V (refer to FIG. 5 on page 5)

Note 2: Typical capacitance @ 0V and 14V bias

GENERAL CHARACTERISTICS

Operating temperature: -55°C to +125°C

Storage temperature: -40°C to +85°C

ESD voltage capability (tested per IEC 61000-4-2)

- Contact discharge mode: 8kV (typ), 15kV (max)
- Air discharge mode: 15kV (typ), 25kV (max) [1 pulse: per customer request]

ESD pulse withstand: Typically 100 pulses (tested per IEC 61000-4-2, level 4, and contact method)

Environmental Specifications

Test Conditions	Bias Humidity Test	Thermal Shock	Bias Heat Test	Bias Low Temp Test	Solderability	Solder Heat	Vibration	Mechanical Shock	Solvent Resistance
	@ 85°C @ 85% RH V _{DC} (max) 1000 hours	-55°C to 125°C 30min dwell 1000 cycles	@ 125°C V _{DC} (max) 1000 hours	@ -55°C V _{DC} (max) 1000 hours	250 °C +/- 5 °C 3s +/- 1s	260 °C, 10s	10 to 50Hz, 60s cycle, 2hrs each in X-Y-Z axis	1500G, 0.5ms, X-Y-Z axis 3 times	IPA ultrasonic 300s
Pass/Fail Criteria	I _L ≤ 10μA	I _L ≤ 10μA	I _L ≤ 10μA	I _L ≤ 10μA	95% coverage	90% coverage	No Physical Damage I _L ≤ 10 μA	No Physical Damage I _L ≤ 10 μA	No Physical Damage I _L ≤ 10 μA

FIG 1: CAPACITANCE VS. FREQUENCY (TYPICAL SAMPLE)

(Flat Response of Capacitance over Frequency Range)

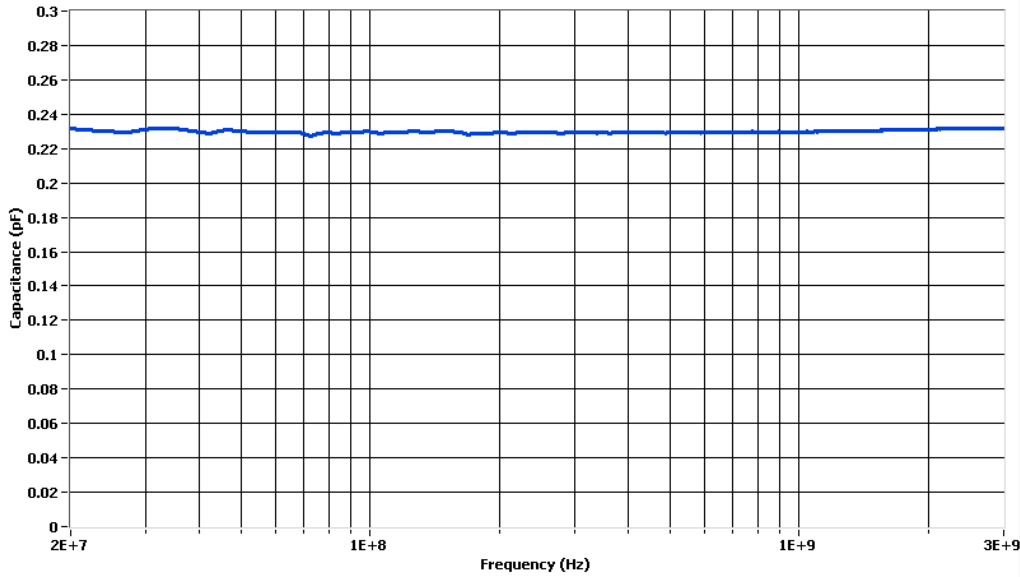


FIG 2: EYE DIAGRAM (TYPICAL SAMPLE)

(Eye Diagram Performance at 3.4 GHz— meets criteria for HDMI 1.4)

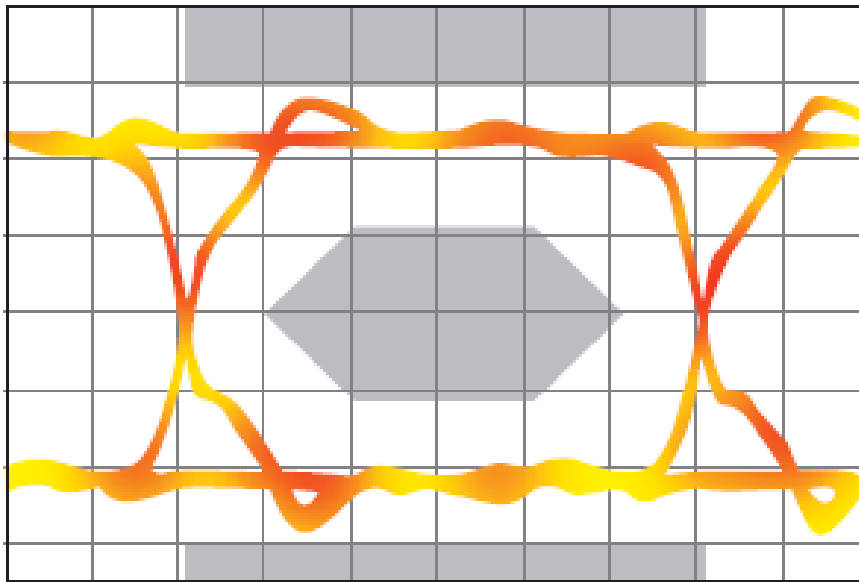


FIG 3: INSERTION LOSS DIAGRAM (TYPICAL SAMPLE)

(Minimal Insertion Loss at 3.4 GHz)

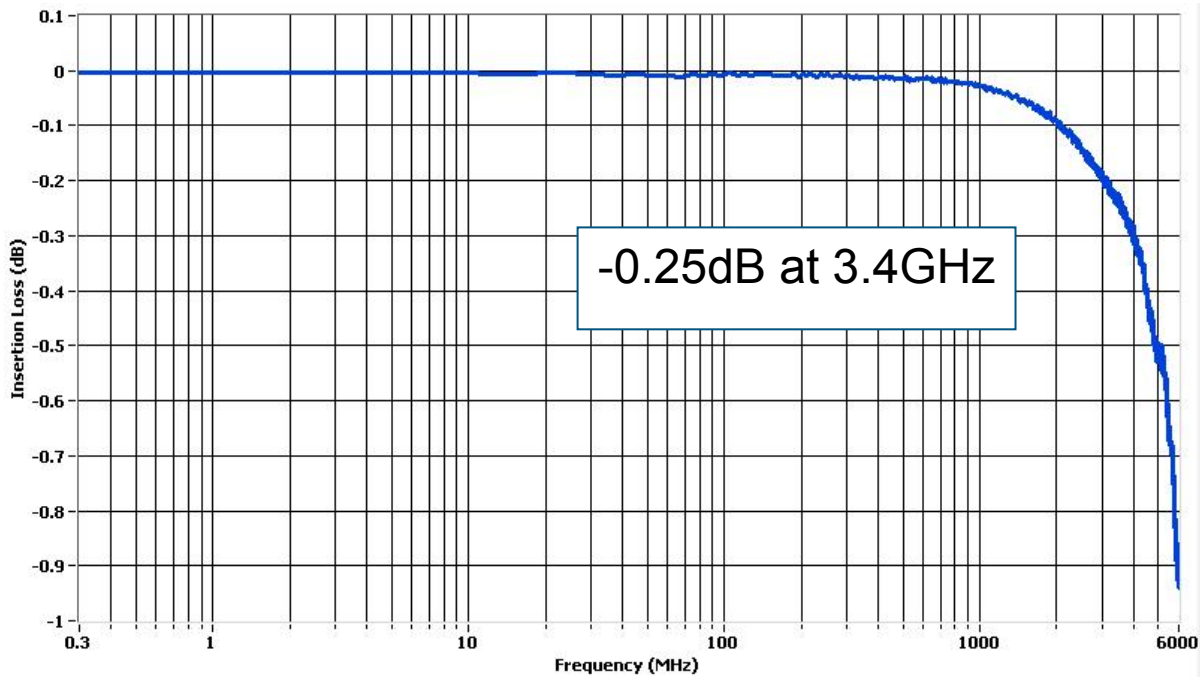


FIG 4: ESD PROTECTION FOR HDMI

(Reference Layout and Test Results available)

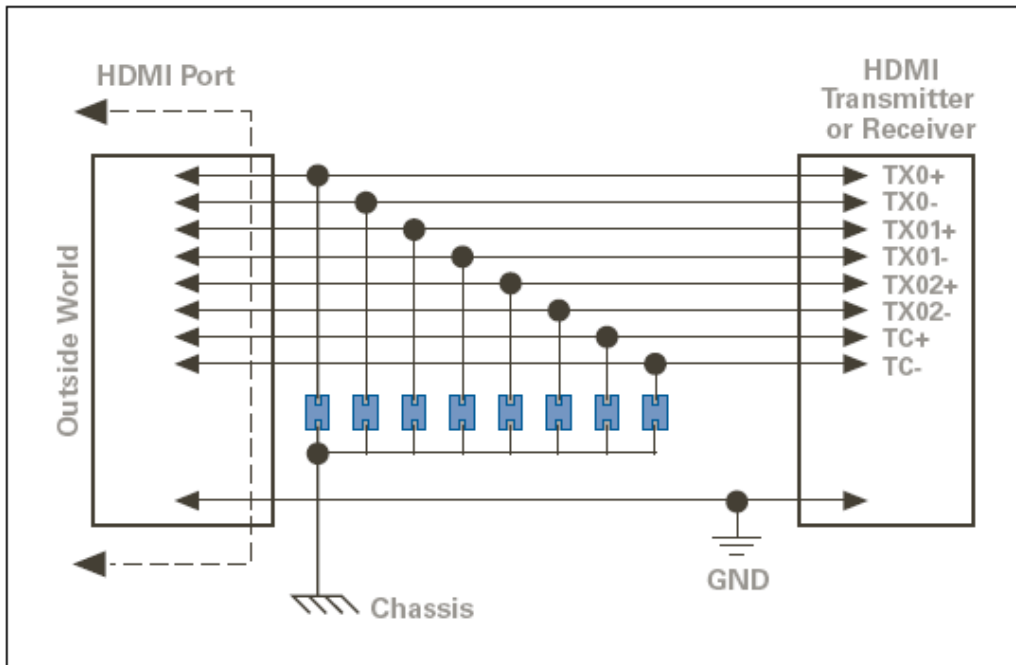
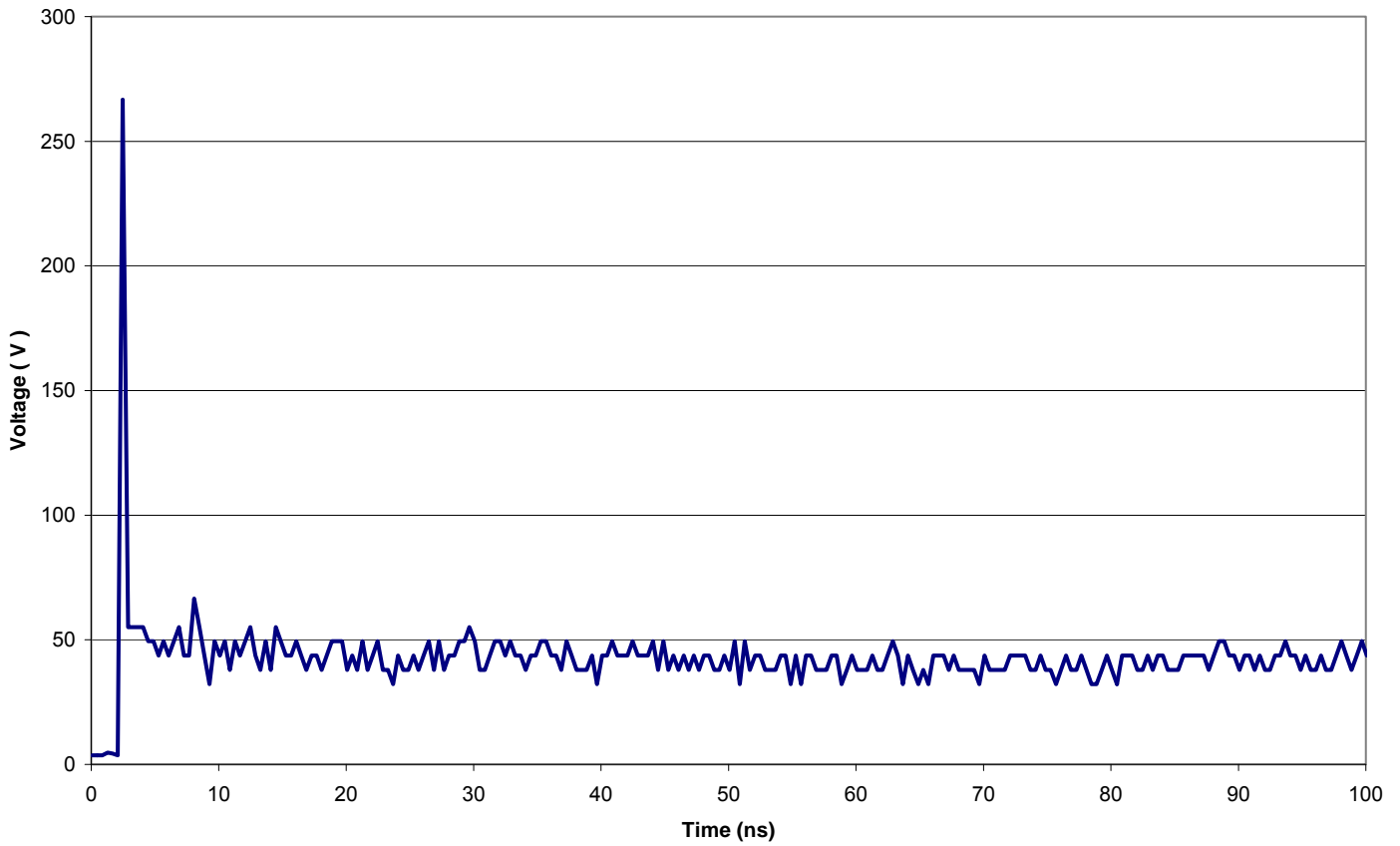
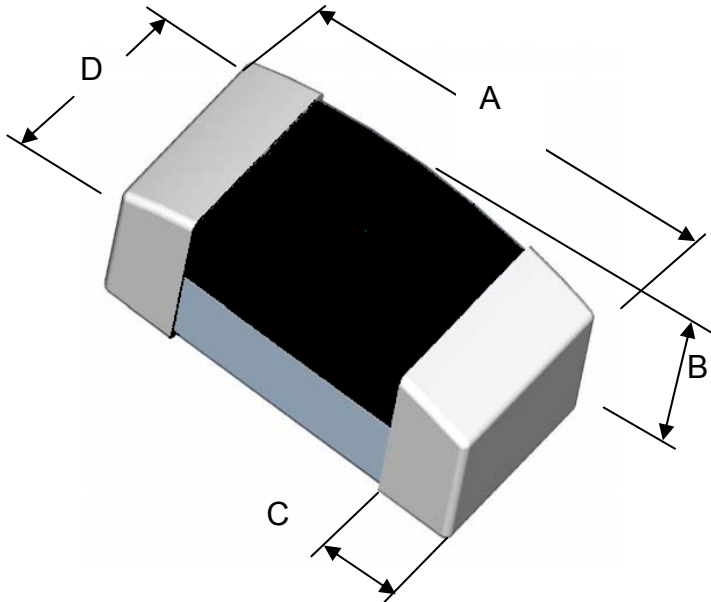


FIG 5: TYPICAL TRANSMISSION LINE PULSE RESPONSE GRAPH

Typical TLP Clamping Voltage



DIMENSIONS

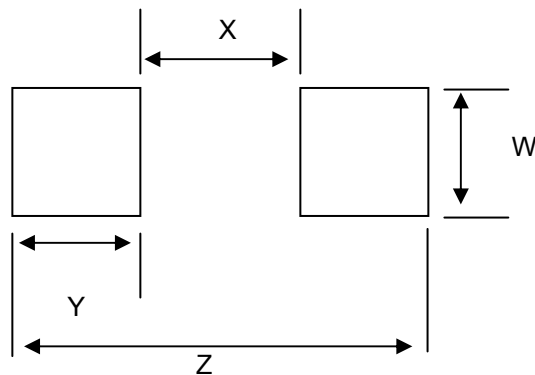


Drawing Not To Scale

	Length A		Height B		Terminal Width C		Width D	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	0.90	1.10	0.23	0.43	0.10	0.30	0.40	0.60
in*	(0.035)	(0.043)	(0.009)	(0.017)	(0.004)	(0.012)	(0.016)	(0.024)

* Round off approximation

RECOMMENDED LAND PATTERN:



	W		X		Y		Z	
	Min	Max	Min	Max	Min	Max	Min	Max
mm	0.60	0.70	0.30	0.40	0.80	0.90	2.10	2.20
in*	(0.024)	(0.028)	(0.012)	(0.016)	(0.031)	(0.035)	(0.083)	(0.087)

* Round off approximation

SOLDER REFLOW RECOMMENDATIONS:

A	Temperature ramp up 1	From ambient to Preheating temperature	30s to 60s
B	Preheating	140°C - 160°C	60s to 120s
C	Temperature ramp up 2	From Preheating to Main heating temperature	20s to 40s
D	Main heating	at 200°C at 220°C at 240°C at 260°C	60s ~ 70s 50s ~ 60s 30s ~ 40s 5s ~ 10s
E	Cooling	From main heating temperature to 100°C	4°C/s (max)

